Diodes Inc. Material Data Sheet
Rev: August 2008

Part Number: **DMN2004K-7**
Weight (mg): 8.29

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.23	0.10	1000000	12257
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.47	2.44	992600	292560
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	796
		Sn	7440-31-5	0.25%			2500	737
		Zn	7440-66-6	0.22%			2200	648
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.25	0.10	1000000	12474
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.31	0.03	1000000	3088
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	66.93	5.55	873000	584285
		Epoxy Resin	29690-82-2	5.00%			50000	33464
		Phenol Resin	26834-02-6	5.00%			50000	33464
		Aromatic poly-phosphate	----	2.50%			25000	16732
		C	1333-86-4	0.20%			2000	1339
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	0.82	0.07	1000000	8155
				Total	100.00	8.29		1000000

Tolerance ±10%

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ˆ The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of

This product or product family does not contain any of the following substances except as**CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN2005K-7**
Weight (mg): 8.72

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	0.97	0.08	1000000	9687
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	30.16	2.63	992600	299363
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	814
		Sn	7440-31-5	0.25%			2500	754
		Zn	7440-66-6	0.22%			2200	664
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.19	0.10	1000000	11853
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	0.29	0.03	1000000	2935
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	64.07	5.59	873000	559329
		Epoxy Resin	29690-82-2	5.00%			50000	32035
		Phenol Resin	26834-02-6	5.00%			50000	32035
		Aromatic poly-phosphate	----	2.50%			25000	16017
		C	1333-86-4	0.20%			2000	1281
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	0.39	0.03	750000	2958
		epoxy resin	Trade secret	20.00%			200000	789
		curing agent & hardener	Trade secret	5.00%			50000	197
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.93	0.26	1000000	29289
				Total	100.00	8.72		1000000

Tolerance ±10%

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Antimony Compounds
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Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN2050L-7**
Weight (mg): 8.95

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	5.46	0.49	1000000	54577
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.39	2.63	992600	291760
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	794
		Sn	7440-31-5	0.25%			2500	735
		Zn	7440-66-6	0.22%			2200	647
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.16	0.10	1000000	11552
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	1.32	0.12	1000000	13172
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	57.60	5.16	873000	502824
		Epoxy Resin	29690-82-2	5.00%			50000	28799
		Phenol Resin	26834-02-6	5.00%			50000	28799
		Aromatic poly-phosphate	----	2.50%			25000	14399
		C	1333-86-4	0.20%			2000	1152
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	2.22	0.20	750000	16683
		epoxy resin	Trade secret	20.00%			200000	4449
		curing agent & hardener	Trade secret	5.00%			50000	1112
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.85	0.26	1000000	28546
				Total	100.00	8.95		1000000

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Antimony Compounds
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Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:

Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN2104L-7**
Weight (mg): 8.88

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.75	0.33	1000000	37193
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.63	2.63	992600	291760
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	794
		Sn	7440-31-5	0.25%			2500	735
		Zn	7440-66-6	0.22%			2200	647
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.16	0.10	1000000	11552
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	1.33	0.12	1000000	13172
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	59.72	5.30	873000	502824
		Epoxy Resin	29690-82-2	5.00%			50000	28799
		Phenol Resin	26834-02-6	5.00%			50000	28799
		Aromatic poly-phosphate	----	2.50%			25000	14399
		C	1333-86-4	0.20%			2000	1152
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	1.53	0.14	750000	16683
		epoxy resin	Trade secret	20.00%			200000	4449
		curing agent & hardener	Trade secret	5.00%			50000	1112
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.88	0.26	1000000	28777
				Total	100.00	8.88		982847

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Antimony Compounds
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Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
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Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN2170U-7**
Weight (mg): 8.89

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.80	0.34	1000000	37991
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.58	2.63	992600	293611
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	799
		Sn	7440-31-5	0.25%			2500	739
		Zn	7440-66-6	0.22%			2200	651
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.16	0.10	1000000	11626
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	0.97	0.09	1000000	9725
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	60.06	5.34	873000	524367
		Epoxy Resin	29690-82-2	5.00%			50000	30032
		Phenol Resin	26834-02-6	5.00%			50000	30032
		Aromatic poly-phosphate	----	2.50%			25000	15016
		C	1333-86-4	0.20%			2000	1201
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	1.55	0.14	750000	11611
		epoxy resin	Trade secret	20.00%			200000	3096
		curing agent & hardener	Trade secret	5.00%			50000	774
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.87	0.26	1000000	28727
				Total	100.00	8.89		1000000

Tolerance ±10%

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Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN2230U-7**
Weight (mg): 8.87

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.29	0.29	1000000	32875
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.65	2.63	992600	294309
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	801
		Sn	7440-31-5	0.25%			2500	741
		Zn	7440-66-6	0.22%			2200	652
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.17	0.10	1000000	11653
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	0.97	0.09	1000000	9749
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	60.70	5.39	873000	529933
		Epoxy Resin	29690-82-2	5.00%			50000	30351
		Phenol Resin	26834-02-6	5.00%			50000	30351
		Aromatic poly-phosphate	----	2.50%			25000	15176
		C	1333-86-4	0.20%			2000	1214
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	1.34	0.12	750000	10050
		epoxy resin	Trade secret	20.00%			200000	2680
		curing agent & hardener	Trade secret	5.00%			50000	670
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.88	0.26	1000000	28795
				Total	100.00	8.87		1000000

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Ozone Depleting Substances - Class II (HCFCs)
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Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN305xL SOT23 Green**
Weight (mg): 8.96

PART NUMBERS: **DMN3051L-7, DMN3053L-7**

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	5.70	0.51	1000000	57013
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.37	2.63	992600	291477
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	793
		Sn	7440-31-5	0.25%			2500	734
		Zn	7440-66-6	0.22%			2200	646
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.15	0.10	1000000	11541
Bond Wire	Copper Wire	Copper	7440-50-8	100.00%	1.32	0.12	1000000	13160
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	57.32	5.14	873000	500387
		Epoxy Resin	29690-82-2	5.00%			50000	28659
		Phenol Resin	26834-02-6	5.00%			50000	28659
		Aromatic poly-phosphate	----	2.50%			25000	14330
		C	1333-86-4	0.20%			2000	1146
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	2.29	0.21	750000	17203
		epoxy resin	Trade secret	20.00%			200000	4587
		curing agent & hardener	Trade secret	5.00%			50000	1147
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.85	0.26	1000000	28518
				Total	100.00	8.96		1000000

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Hexavalent chromium compounds
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Mercury and mercury compounds
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Ozone Depleting Substances - Class II (HCFCs)
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Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN3150L-7**
Weight (mg): 9.00

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.70	0.33	1000000	36995
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.24	2.63	992600	290207
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	789
		Sn	7440-31-5	0.25%			2500	731
		Zn	7440-66-6	0.22%			2200	643
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.15	0.10	1000000	11491
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	2.27	0.20	1000000	22748
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	59.29	5.34	873000	517620
		Epoxy Resin	29690-82-2	5.00%			50000	29646
		Phenol Resin	26834-02-6	5.00%			50000	29646
		Aromatic poly-phosphate	----	2.50%			25000	14823
		C	1333-86-4	0.20%			2000	1186
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	1.51	0.14	750000	11310
		epoxy resin	Trade secret	20.00%			200000	3016
		curing agent & hardener	Trade secret	5.00%			50000	754
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.84	0.26	1000000	28394
				Total	100.00	9.00		1000000

Tolerance ±10%

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ˆ The Silicon Chip is doped at atomic levels with trace amounts of elements that may include Phosphorus, Boron, Arsenic, and other elements. Metalization may include Titanium, Nickel, Aluminum, Silver or Gold These substances are not reported where their concentration is less than the minimum reportable level per the guidelines specified in the Tables of

This product or product family does not contain any of the following substances except as**CURRENTLY** exempted by ELV II and RoHS and reported above:

Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN3200U-7**
Weight (mg): 8.89

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.80	0.34	1000000	37991
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.58	2.63	992600	293611
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	799
		Sn	7440-31-5	0.25%			2500	739
		Zn	7440-66-6	0.22%			2200	651
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.16	0.10	1000000	11626
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.97	0.09	1000000	9725
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	60.06	5.34	873000	524367
		Epoxy Resin	29690-82-2	5.00%			50000	30032
		Phenol Resin	26834-02-6	5.00%			50000	30032
		Aromatic poly-phosphate	----	2.50%			25000	15016
		C	1333-86-4	0.20%			2000	1201
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	1.55	0.14	750000	11611
		epoxy resin	Trade secret	20.00%			200000	3096
		curing agent & hardener	Trade secret	5.00%			50000	774
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.87	0.26	1000000	28727
				Total	100.00	8.89		1000000

Tolerance ±10%

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Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN3300U-7**
Weight (mg): 8.87

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	3.29	0.29	1000000	32875
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	29.65	2.63	992600	294309
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	801
		Sn	7440-31-5	0.25%			2500	741
		Zn	7440-66-6	0.22%			2200	652
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.17	0.10	1000000	11653
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.97	0.09	1000000	9749
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	60.70	5.39	873000	529933
		Epoxy Resin	29690-82-2	5.00%			50000	30351
		Phenol Resin	26834-02-6	5.00%			50000	30351
		Aromatic poly-phosphate	----	2.50%			25000	15176
		C	1333-86-4	0.20%			2000	1214
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	1.34	0.12	750000	10050
		epoxy resin	Trade secret	20.00%			200000	2680
		curing agent & hardener	Trade secret	5.00%			50000	670
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.88	0.26	1000000	28795
				Total	100.00	8.87		1000000

Tolerance ±10%

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Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN5L06-7**
Weight (mg): 8.74

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.49	0.13	1000000	14946
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	30.08	2.63	992600	298623
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	812
		Sn	7440-31-5	0.25%			2500	752
		Zn	7440-66-6	0.22%			2200	662
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.18	0.10	1000000	11824
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.29	0.03	1000000	2927
Encapsulation	CEL-1702HF9	SiO2	60676-86-0	87.30%	63.41	5.55	873000	553565
		Epoxy Resin	29690-82-2	5.00%			50000	31705
		Phenol Resin	26834-02-6	5.00%			50000	31705
		Aromatic poly-phosphate	----	2.50%			25000	15852
		C	1333-86-4	0.20%			2000	1268
Die Attach Epoxy	84-1LMISR4	Ag	7440-22-4	75.00%	0.61	0.05	750000	4606
		epoxy resin	Trade secret	20.00%			200000	1228
		curing agent & hardener	Trade secret	5.00%			50000	307
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	2.92	0.26	1000000	29217
				Total	100.00	8.74		1000000

Tolerance ±10%

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Asbestos
Antimony Compounds
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Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN5L06K-7**
Weight (mg): 8.51

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.88	0.16	1000000	18762
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	28.70	2.44	992600	284903
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	775
		Sn	7440-31-5	0.25%			2500	718
		Zn	7440-66-6	0.22%			2200	631
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.21	0.10	1000000	12147
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.30	0.03	1000000	3007
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	64.90	5.52	690000	447838
		Epoxy Resin	29690-82-2	14.00%			140000	90866
		Phenol Resin	9003-35-4	7.00%			70000	45433
		Mg(OH)2	1309-42-8	8.00%			80000	51923
		C	1333-86-4	0.20%			2000	1298
		others	----	1.80%			18000	11683
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	3.00	0.26	1000000	30016
				Total	100.00	8.51		1000000

Tolerance ±10%

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Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate

Part Number: **DMN601K-7**
Weight (mg): 8.51

Element	Material Group	Materials	CAS (if applicable)	Average mass homogeneous Materal(%)	Percent of whole (%)	Mass (mg)	ppm Homogeneous Material	ppm overall
Chip	Silicon w/Metal	Doped Silicon*	7440-21-3	100.00%	1.88	0.16	1000000	18762
Leadframe	EFTEC-64T	Cu	7440-50-8	99.26%	28.70	2.44	992600	284903
		Cr(not Cr 6+)	7440-47-3	0.27%			2700	775
		Sn	7440-31-5	0.25%			2500	718
		Zn	7440-66-6	0.22%			2200	631
Leadframe Plating	Silver	Silver	7440-22-4	100.00%	1.21	0.10	1000000	12147
Bond Wire	Gold Wire	Gold	7440-57-5	100.00%	0.30	0.03	1000000	3007
Encapsulation	KTMC-1050G	SiO2	60676-86-0	69.00%	64.90	5.52	690000	447838
		Epoxy Resin	29690-82-2	14.00%			140000	90866
		Phenol Resin	9003-35-4	7.00%			70000	45433
		Mg(OH)2	1309-42-8	8.00%			80000	51923
		C	1333-86-4	0.20%			2000	1298
		others	----	1.80%			18000	11683
Lead Plating Finish	Matte Tin	Tin	7440-31-5	100.00%	3.00	0.26	1000000	30016
				Total	100.00	8.51		1000000

Tolerance ±10%

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Asbestos
Antimony Compounds
Azo compounds
Cadmium and cadmium compounds
Certain Shortchain Chlorinated Paraffins
Chlorinated organic compounds
Halogens
Hexavalent chromium compounds
Lead and lead compounds
Mercury and mercury compounds
Organic tin compounds
Ozone Depleting Substances - Class I (CFCs, HBFCs, etc.)
Ozone Depleting Substances - Class II (HCFCs)
Perfluorooctane Sulphonate (PFOS) or related compounds
Polybrominated biphenyls (PBB) and Polybrominated diphenyl ethers (PBDE) including DecaBDE
Polychlorinated Biphenyls (PCBs)
Polychlorinated Naphthalenes (> 3 chlorine atoms)
Radioactive Substances
Tributyl Tin (TBT) and Triphenyl Tin (TPT)
Tributyl Tin Oxide (TBTO)

REACH SVHCs:
Anthracene
4,4'- Diaminodiphenylmethane
Dibutyl phthalate
Cyclododecane
Cobalt dichloride
Diarsenic pentaoxide
Diarsenic trioxide
Sodium dichromate, dihydrate
5-tert-butyl-2,4,6-trinitro-m-xylene (musk xylene)
Bis (2-ethyl(hexyl)phthalate) (DEHP)
Hexabromocyclododecane (HBCDD)
Alkanes, C10-13, chloro (Short Chain Chlorinated Paraffins)
Bis(tributyltin)oxide
Lead hydrogen arsenate
Triethyl arsenate
Benzyl butyl phthalate